Special Issue

Advances in Atomic Layer Etching

Message from the Guest Editor

Dear colleagues, Depending on the scaling down of electronic and optoelectronic devices and the complexity of the process, the technology that can precisely etch semiconductor materials has become a very important factor. In addition, two-dimensional materials (graphene and transition metal dichalcogenides) require a damage-free etching technique because semiconductor properties change depending on the number of layers. Atomic layer etching is a key technology for the development of nextgeneration semiconductor devices because it can be etched while minimizing material damage through stepby-step surface reaction. Accordingly, this Special Issue seeks to showcase research papers, communications and review articles that focus on novel methodologies for atomic layer etching, optimization of processes and their applications.

Guest Editor

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Deadline for manuscript submissions

closed (25 July 2021)



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Editor-in-Chief

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